



March 18, 2017

To: Conexant Customer

Subject: Conexant Semiconductor Product RoHS and RoHS 2 Compliance Statement

Conexant is a strong supporter of worldwide environmental initiatives. Conexant's "Lead-Free and RoHS" semiconductor products meet the relevant materials content established by Joint Industry Guide (JIG-101) Edition. 4.1, Directive 2002/95/EC (RoHS), Directive 2011/65/EU (RoHS2), and SJ/T 11363 – 2006 (China RoHS). In addition to meeting these compliance obligations, homogeneous materials in Conexant products do not contain substances or compounds in excess of the limits indicated in the table below:

	Element/Compound	Limit
Directive 2002/95/EC RoHS Directive 2011/65/EU RoHS2 SJ/T 11363 – 2006	Lead and its Compounds	1000 ppm
	Mercury and its Compounds	1000 ppm
	Cadmium and its Compounds	100 ppm
	Hexavalent Chromium and its Compounds	1000 ppm
	Polybrominated Biphenyls (PBB's)	1000 ppm
	Polybrominated Diphenyl Ethers (PBDE's, including Deca-BDE)	1000 ppm
	Bis(2-ethylhexyl) phthalate (DEHP)	1000 ppm
	Butyl benzyl phthalate (BBP)	1000 ppm
	Dibutyl phthalate (DBP)	1000 ppm
	Diisobutyl phthalate (DIBP)	1000 ppm
PFOS Compliant (Directive 2006/122/EC)	Perfluorooctane sulfonates—PFOS Exemptions: Photoresists or anti-reflective coatings for photolithography processes	1000 ppm
Halogen/BFR/PVC Free	Halogens, including Brominated Flame Retardants (other than PBB/PBDE) and PVC Compounds	900 ppm

Conexant's lead-free leadframe-based packages are backward compatible to standard lead-based solder PCB assembly processes. This means that leadframe-based components with matte tin finish have the same form, fit, and function as standard lead-based components, and the components can be attached to a PCB using eutectic tin/lead solder paste with a standard tin/lead solder profile. Lead-free BGA components are not compatible with the standard tin/lead solder PCB assembly processes.

Conexant requires that our suppliers minimize tin-whisker formation by heat-treating all leadframe-based lead-free packages with the industry-standard post-plate bake step (150C, 1 hour). We recommend our customers follow the JEDEC reflow soldering profiles referenced in J-STD-020C.

Conexant typically identifies Pb-Free, RoHS, RoHS2 compliant products with a "Z" suffix at the end of the product dash number. In addition, IC packages are marked in compliance with requirements established in JEDEC Standard JESD97.

NOTE: Conexant's position is that Semiconductor products are considered components in RoHS1 and RoHS2. Therefore, CE Marking, Declaration of Conformity, and internal product control provisions stipulated in 2011/65/EU (RoHS2) Article 7 do not apply.

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